

S/N 09/253,611



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Patar

Examiner: Ron Pompey

Serial No.: 09/253,611

Group Art Unit: 2812

Filed: February 19, 1999

Docket: 303.572US1

Title: SELECTIVE DEPOSITION OF SOLDER BALL CONTACTS

AMENDMENT AND RESPONSE

Assistant Commissioner for Patents
Washington, D.C. 20231

4/a
7/10/00
V. Varnall

Applicant has reviewed the Office Action mailed on March 31, 2000. Please amend the above-identified patent application as follows.

IN THE SPECIFICATION

Please amend the specification as follows:

At page 3, line 28, please delete "then" and insert in place thereof -than-

IN THE CLAIMS

Please cancel claims 24-63 without prejudice or disclaimer thereto.

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Please amend the claims as follows:

1. (Amended) A method of forming a solder ball contact, comprising:
- forming a metal contact pad on a substrate;
 - forming an insulating layer on the metal contact pad;
 - removing a portion of the insulating layer to expose a portion of the metal contact pad,
- thereby forming an exposed portion of the metal contact pad, the exposed portion having a predetermined diameter;
- immersing the substrate in molten solder;
 - depositing solder on the exposed portion of the metal contact pad using selective deposition, thereby forming a solder contact; and
 - annealing the solder contact to form a solder ball contact.

Sub
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A.
C. Patar